

PATENT ABSTRACTS OF JAPAN

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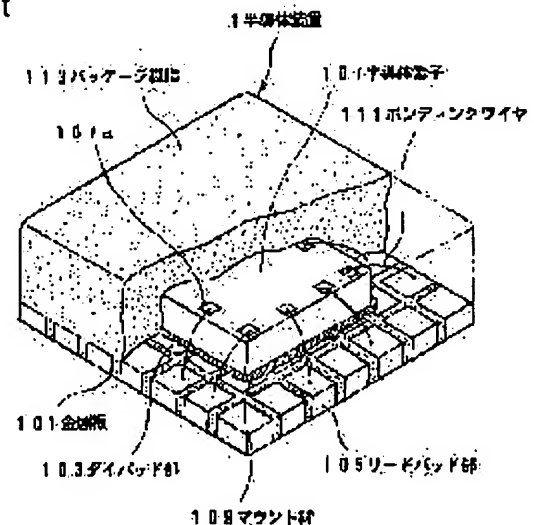
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(54) SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a surface mount semiconductor device having a leadless structure allowing components to be commonly used for different kinds and sizes of semiconductor devices and its manufacturing method.

SOLUTION: Grooves 131 are formed in grid on the surface of a metal plate 101 to section a plurality of divided pieces 133, some of the plurality of divided pieces are used as die pads 103 to mount a semiconductor element 107 with mount members 109, other divided pieces are used as lead pads 105 to electrically connected the semiconductor element 107 through bonding wires 111, the semiconductor element 107 and the bonding wires 111 are sealed with a package resin 113, the backside of the metal plate 101 is polished up to the bottoms of the grooves 131, thus separating the divided pieces 133. According to the size or kind of semiconductor elements, divided pieces constituted as die pads and lead pads are adequately set and the package resin is cut at desired part to realize a leadless and surface mount semiconductor device of a desired size/ kind.



LEGAL STATUS

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